



## Material Content Data Sheet



Sales Product Name	ESD0P2RF-02LS E6327			Issued		29. August 2013		
MA#	MA000879164							
Package	PG-TSSLP-2-1			Weight*		0.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.45		4500	
	noble metal	gold	7440-57-5	0.003	1.75		17463	
	inorganic material	silicon	7440-21-3	0.020	12.94	15.14	129395	151358
leadframe	non noble metal	nickel	7440-02-0	0.036	23.48	23.48	234780	234780
wire	noble metal	gold	7440-57-5	0.006	3.59	3.59	35862	35862
encapsulation	organic material	carbon black	1333-86-4	0.001	0.50		5036	
	plastics	epoxy resin	-	0.011	6.80		67961	
	inorganic material	silicondioxide	60676-86-0	0.067	43.03	50.33	430438	503435
leadfinish	noble metal	gold	7440-57-5	0.004	2.66	2.66	26553	26553
plating	noble metal	silver	7440-22-4	0.007	4.80	4.80	48012	48012
*deviation	< 10%	Sum in total:				100,00		1000000

### Important Remarks:

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